

Multi-Chip Combi Card Inlay

Separate chip functions in one card

These two-chip configurations are engineering references built from manufacturer IC specifications. They are not stock assemblies or evidence of RF coexistence. A quotation defines the supplied chips, antenna layout and sample qualification.

Reference / technology	Separate chip data	Application & conditions
NTAG213 + MIFARE DESFire EV3 HF + HF: two 13.56 MHz ICs. NTAG213 uses NFC Type 2; DESFire EV3 uses ISO/IEC 14443-4 / NFC Type 4.	NTAG213: 144 bytes user memory. DESFire EV3: 2 / 4 / 8 / 16 kB non-volatile memory, by variant. Separate memory areas.	A candidate for a public NFC link alongside a separately managed DESFire access application. The reader must select the intended IC and use its commands. Test phone selection as well as access-reader transactions; two chips at 13.56 MHz do not guarantee the intended tap result.
EM4200 + NTAG213 LF + HF: an EM4200 coil specified for a 125 kHz reader plus a 13.56 MHz NFC Type 2 circuit.	EM4200: factory-programmed ROM, 128-bit with 64 / 96-bit options. NTAG213: 144 bytes user memory. No shared memory.	A candidate for an existing LF identifier and a separate NFC phone link in the same credential. Choose the EM4200 variant and returned ID format first. Its fixed identifier and the NFC data are linked in the application database, not automatically by the inlay.

Component package references

NTAG213 bare-die references. NT2H1311G0DUF: 75 µm wafer thickness; NT2H1311G0DUD: 120 µm. Both are 144-byte, 50 pF references. These are die values, not inlay thickness.

DESFire EV3 module reference. MF3D4300DA4/00: 4 kB, 17 pF, MOA4 / SOT500-2. The module outline and assembled bond height govern the local cavity; its memory size does not define clearance.

Image evidence: the product page retains the original sheet photograph and a 4 × 3 layout illustration. The illustration shows twelve card positions; it does not establish supplied dimensions or chip identity.

Sources & scope

[NTAG213 / NTAG215 / NTAG216 datasheet](#) NXP Semiconductors

[MIFARE DESFire EV3 short datasheet](#) NXP Semiconductors

[EM4200 datasheet](#) EM Microelectronic

This technical reference compares documented components or historical connection methods. It does not establish current availability, tested compatibility of a combined assembly, production dimensions, MOQ or lead time. The order drawing and quotation define the supplied configuration.

[View product photographs, engineering references and configuration inquiry →](#)